

5 **PROCESSING OF CIRCUIT BOARDS WITH PROTECTIVE, ADHESIVE-
LESS COVERS ON AREA ARRAY BONDING SITES**

Abstract of the Disclosure

10 An apparatus, program product and method for processing circuit boards
containing area array surface treated bonding sites, such as noble metal terminal pads
of a Land Grid Array (LGA) assembly. The circuit board includes a plurality of
apertures patterned about the bonding site for form a footprint. A protective cover
shaped to conform to the footprint includes posts registered to removably fit into the
apertures. The protective cover remains overlaid on the circuit board during
15 fabrication processes such as solder screen printing, rework, and washing, and then
removed. Thus, contamination from the fabrication processes is avoided, as well as
eliminating possible sources of contamination from use of adhesive tape for
protection.